

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	204	(ash\$3 with atmospheric with pressure)	US-PGPUB; USPAT	OR	ON	2005/03/10 12:21
L2	2170	((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/03/10 12:15
L3	8	1 and 2	US-PGPUB; USPAT	OR	ON	2005/03/10 12:15
L4	84	((transfer\$4 convey\$3 transport\$4) with chamber with atmospheric with pressure) and (ash\$3 with chamber)	US-PGPUB; USPAT	OR	ON	2005/03/10 12:24
L5	9	((transfer\$4 convey\$3 transport\$4) with chamber with atmospheric with pressure) same (ash\$3 with chamber)	US-PGPUB; USPAT	OR	ON	2005/03/10 12:28
L6	4	((transfer\$4 convey\$3 transport\$4) with chamber with atmospheric with pressure) same (ash\$3 with chamber)	EPO; JPO; DERWENT	OR	ON	2005/03/10 13:05
L7	1	("5796952").PN.	US-PGPUB; USPAT	OR	OFF	2005/03/10 13:05
L8	1	("5769952").PN.	US-PGPUB; USPAT	OR	OFF	2005/03/10 13:54
L9	0	("576995220010024691").PN.	US-PGPUB; USPAT	OR	OFF	2005/03/10 13:54
L10	1	("20010024691").PN.	US-PGPUB; USPAT	OR	OFF	2005/03/10 13:54
L12	47	verhaverbeke-steven.in. truman-j-kelly.in. lane-christopher-t.in.	US-PGPUB; USPAT	OR	ON	2005/03/10 14:33
S1	208	("118"/\$.ccls. 156/345.\$.ccls.) and ((monitor\$3 determin\$3 measure\$3) with (particle particulate debris) with surface)	US-PGPUB; USPAT	OR	ON	2005/03/10 12:14
S2	2550	("118"/\$.ccls. 156/345.\$.ccls.) and ((monitor\$3 determin\$3 measure\$3) with (thickness))	US-PGPUB; USPAT	OR	ON	2003/08/08 12:32
S3	1414	("118"/\$.ccls. 156/345.\$.ccls.) and ((monitor\$3 measure\$3) with (thickness))	US-PGPUB; USPAT	OR	ON	2003/08/08 12:32
S4	113	("118"/\$.ccls. 156/345.\$.ccls.) and ((monitor\$3 measure\$3) with (particle particulate debris) with surface)	US-PGPUB; USPAT	OR	ON	2003/08/08 13:09
S5	9	"5837094".URPN.	USPAT	OR	ON	2003/08/08 12:45
S6	999	(monitor\$3 measure\$3 detect\$3) with (particle particulate debris) with surface with (wafer substrate semiconductor)	US-PGPUB; USPAT	OR	ON	2003/08/08 19:50
S7	48978	c23c016\$.ipc.	EPO; JPO; DERWENT	OR	ON	2003/08/08 13:36
S8	0	(monitor\$3 measure\$3 detect\$3) with (particle particulate debris) with surface with (wafer substrate semiconductor)	EPO; JPO; DERWENT	OR	ON	2003/08/08 13:11
S9	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/08/08 13:32
S10	1752	((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/03/10 12:15
S11	105	((((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.) and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	US-PGPUB; USPAT	OR	ON	2003/08/08 13:36
S12	48978	c23c016\$.ipc.	EPO; JPO; DERWENT	OR	ON	2003/08/08 13:36
S13	59	"4693777".URPN.	USPAT	OR	ON	2003/08/08 13:55
S14	103	c23c016\$.ipc. and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	OR	ON	2004/10/07 15:13
S15	2	09/945,454	US-PGPUB; USPAT	OR	ON	2003/08/08 15:42

S16	2	09/945454	US-PGPUB; USPAT	OR	ON	2003/08/08 15:42
S17	121	((transfer\$4 transport\$3) with chamber) and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	OR	ON	2004/10/07 15:13
S18	2388	((transfer\$4 transport\$3) with chamber) and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	US-PGPUB; USPAT	OR	ON	2003/08/08 15:54
S19	122	((transfer\$4 transport\$3) with chamber) with ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	US-PGPUB; USPAT	OR	ON	2003/08/08 15:54
S20	57	((transfer\$4 transport\$3) with chamber) with ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	OR	ON	2003/08/08 15:55
S21	76	((transfer\$4 transport\$3) with chamber) same ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	OR	ON	2004/10/07 15:13
S22	194	((transfer\$4 transport\$3) with chamber) same ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	US-PGPUB; USPAT	OR	ON	2003/08/08 16:28
S23	2	118/719.ccls. and imahashi.in.	US-PGPUB; USPAT	OR	ON	2003/08/08 17:01
S24	1	("5909276").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/08/08 20:03
S25	1752	((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/08/08 19:59
S26	11	((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.) and (ash\$3 with atmospher\$3 with pressure)	US-PGPUB; USPAT	OR	ON	2003/08/08 19:57
S27	324	ash\$3 with atmospher\$3 with pressure	US-PGPUB; USPAT	OR	ON	2003/08/08 19:57
S28	139	ash\$3 with "atmospheric pressure"	US-PGPUB; USPAT	OR	ON	2003/08/08 19:57
S29	76	ash\$3 with "atmospheric pressure"	EPO; JPO; DERWENT	OR	ON	2003/08/08 19:58
S30	1	c23c016\$.ipc. and (ash\$3 with "atmospheric pressure")	EPO; JPO; DERWENT	OR	ON	2003/08/08 19:59
S31	11	(chamber with ash\$3 with "atmospheric pressure")	EPO; JPO; DERWENT	OR	ON	2003/08/08 19:59
S32	23	(ashing with "atmospheric pressure")	EPO; JPO; DERWENT	OR	ON	2003/08/08 20:00
S33	2	"06177093"	EPO; JPO; DERWENT	OR	ON	2003/08/10 16:17
S34	0	"integrated particle monitor" with laser with reflect\$4	US-PGPUB; USPAT	OR	ON	2004/10/07 13:24
S35	0	"integrated particle monitor" same laser same reflect\$4	EPO; JPO; DERWENT	OR	ON	2004/10/07 13:24
S36	2	"integrated particle monitor" same laser same reflect\$4	US-PGPUB; USPAT	OR	ON	2004/10/07 13:25
S37	25	"integrated particle monitor"	US-PGPUB; USPAT	OR	ON	2004/10/07 13:29
S38	2	"integrated particle monitor" same laser	US-PGPUB; USPAT	OR	ON	2004/10/07 13:25
S39	83	((monitor\$4 detect\$4 measur\$4 observ\$4) with (particle) with laser with reflect\$4) same (wafer substrate workpiece semiconductor)	US-PGPUB; USPAT	OR	ON	2004/10/07 13:31
S40	24	((monitor\$4 detect\$4 measur\$4 observ\$4) with (particle) with laser with reflect\$4) same (wafer substrate workpiece semiconductor)	EPO; JPO; DERWENT	OR	ON	2004/10/07 14:17
S41	1	("4669875").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/10/07 14:17

S42	127	((transfer\$4 transport\$3) with chamber) and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	OR	ON	2004/10/07 15:13
S43	81	((transfer\$4 transport\$3) with chamber) same ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	OR	ON	2004/10/07 15:13
S44	112	c23c016\$.ipc. and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	OR	ON	2004/10/07 15:14
S45	45	verhaverbeke-steven.in. truman-j-kelly.in. lane-christopher-t.in.	US-PGPUB; USPAT	OR	ON	2005/03/10 14:33
S46	4	(verhaverbeke-steven.in. truman-j-kelly.in. lane-christopher-t.in.) and (particle same monitor\$4)	US-PGPUB; USPAT	OR	ON	2004/10/07 15:15